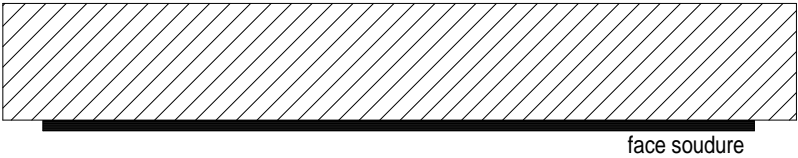


SPEC:

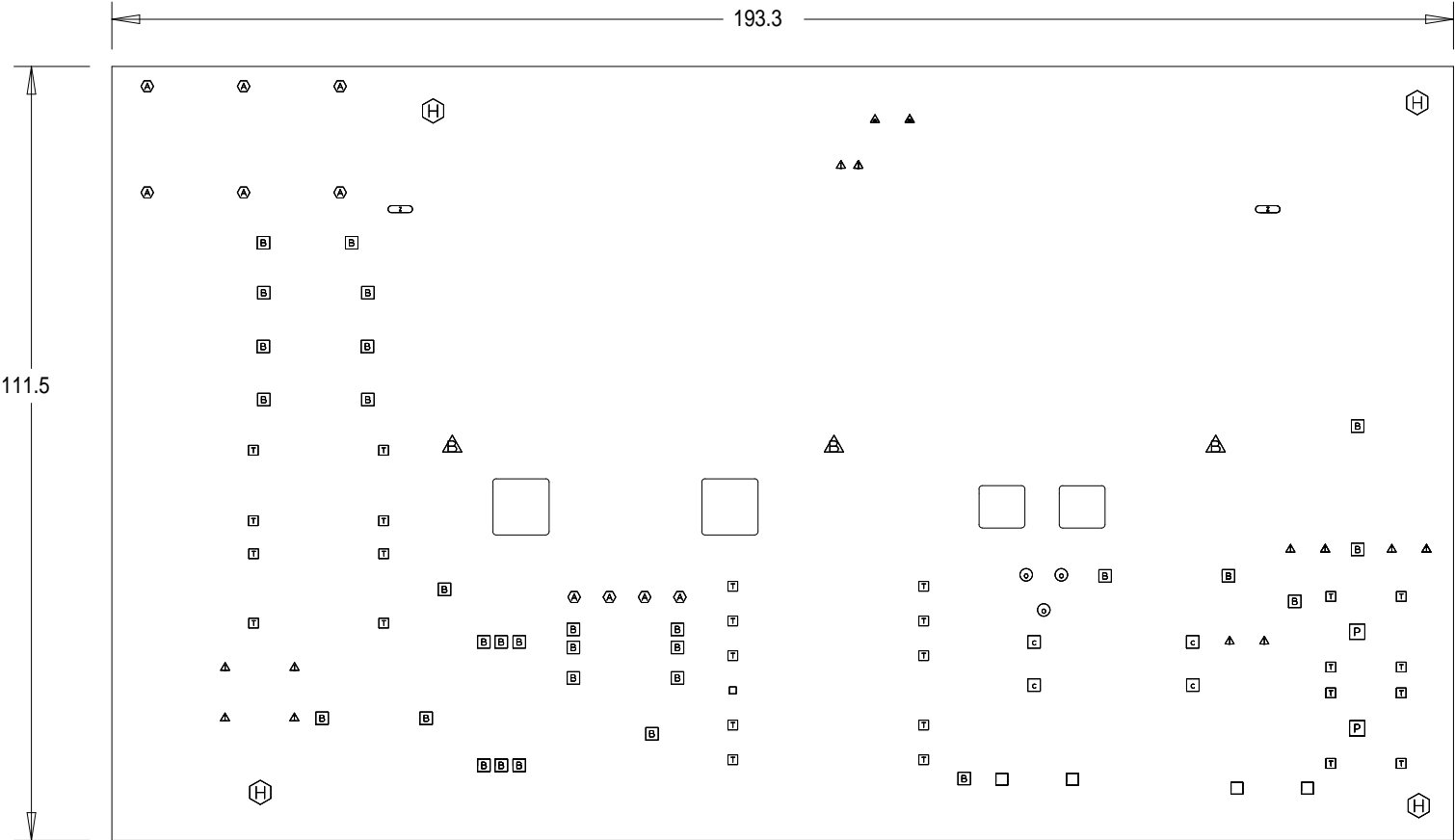
COMPLIANT RoHS DIRECTIVE 2011/65/UE


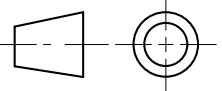
MATERIAL	FR4 IMPROVED (low CTE)
BOARD THICKNESS	1.6mm /63mils
STACKUP	SF /1LAYER
MINIMAL GAP	300um /12.0mils
MINIMAL SLIVER	300um /12.0mils
COPPER THICKNESS	35um(1oz)at START
FINISH THICKNESS	CHEMICAL NiAu
SOLDER MASK	GREEN BOT
SILKSCREEN	WHITE TOP&BOT
ALL BOARD ELECTRICALLY TESTED	
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK	

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
▲	0.8	PLATED	8
▲	0.9	PLATED	4
▣	1.0	PLATED	30
□	1.1	PLATED	4
▣	1.2	PLATED	4
▣	1.4	PLATED	26
▲	1.5	PLATED	2
◎	1.6	PLATED	3
⊙	1.8	PLATED	10
⊞	2.2	PLATED	2
⊞	4.0	PLATED	4
□	1.0	NON-PLATED	1
▲	3.2	NON-PLATED	3
⊞	3.5x1.0	PLATED	2



Pour les details des 4 ouvertures a detourer , voir le gerber outline.art



		W07/2017
indice	Description	Date
Controle par :		Autorise par:
 ON semiconductor		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE 
Board: NCP1622 DEMO A TLS		Subc. DYPE TECH
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